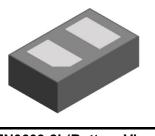


## **Bi-directional 20V Ultra Low Capacitance ESD Protector**

#### **Description**

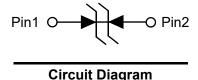
The PESDREC2XD20VBX is an ultra low capacitance ESD protection device specifically designed to protect high-speed lines. It protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. They feature large cross-sectional area junctions for conducting high transient currents, offer desirable electrical characteristics for board level protection, such as fast response time, low operating voltage. It gives designer the flexibility to protect one unidirectional line in applications where arrays are not practical.

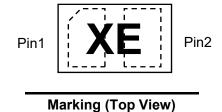


DFN0603-2L(Bottom View)

#### **Feature**

- ➤ Ultra-Low capacitance: 0.15pF
- → 45W peak pulse power per line (t<sub>P</sub> = 8/20µs)
- ➤ DFN0603-2L package
- > Response time is typically < 1 ns
- > Bidirectional configurations
- Low clamping voltage
- > RoHS compliant
- ➤ Transient protection for data lines to IEC 61000-4-2(ESD) ±15kV(air), ± 15kV(contact); IEC 61000-4-5 (Lightning) 6A (8/20us)





#### **Applications**

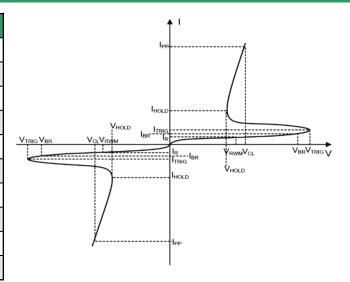
- > Cell phone handsets and accessories
- Personal digital assistants (PDA's)
- Notebooks, desktops, and servers
- > Portable instrumentation
- > Cordless phones
- Digital cameras
- Peripherals

#### **Mechanical Characteristics**

- > Mounting position: Any
- Qualified max reflow temperature:260°C
- > Device meets MSL 1 requirements
- > DFN0603-2L without plating

### **Electronics Parameter**

| Symbol            | Parameter                 |  |  |
|-------------------|---------------------------|--|--|
| $V_{RWM}$         | Reverse stand-off voltage |  |  |
| I <sub>R</sub>    | Reverse leakage current   |  |  |
| $V_{BR}$          | Reverse breakdown voltage |  |  |
| I <sub>BR</sub>   | Reverse breakdown current |  |  |
| V <sub>CL</sub>   | Clamping voltage          |  |  |
| $V_{TRIG}$        | Reverse trigger voltage   |  |  |
| I <sub>TRIG</sub> | Reverse trigger current   |  |  |
| V <sub>HOLD</sub> | Reverse holding voltage   |  |  |
| I <sub>HOLD</sub> | Reverse holding current   |  |  |
| I <sub>PP</sub>   | Peak pulse current        |  |  |



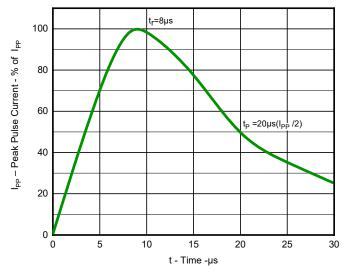
### Electrical characteristics per line@25°C (unless otherwise specified)

| Parameter                        | Symbol           | Conditions                        | Min. | Тур. | Max. | Units |
|----------------------------------|------------------|-----------------------------------|------|------|------|-------|
| Peak Reverse Working Voltage     | $V_{RWM}$        | -                                 | -    | -    | 20   | V     |
| Breakdown Voltage                | $V_{BR}$         | I <sub>t</sub> = 1mA              | 24.5 | 31   | 37   | V     |
| Reverse Leakage Current          | I <sub>R</sub>   | V <sub>RWM</sub> = 20V            | -    | -    | 1.0  | μA    |
| Clamping Voltage                 | V <sub>c</sub>   | $I_{PP} = 1A, t_{P} = 8/20 \mu s$ | -    | 2.5  | 4.0  | V     |
|                                  |                  | $I_{PP} = 6A, t_{P} = 8/20 \mu s$ | -    | 5.6  | 8.0  |       |
| Dynamic resistance <sup>1)</sup> | R <sub>DYN</sub> | -                                 | -    | 0.3  | -    | Ω     |
| Junction Capacitance             | CJ               | $V_R = 0V, f = 1MHz$              | -    | 0.15 | 0.2  | pF    |

# Absolute maximum rating@25°C

| Rating   | Symbol             | Value        | Units |
|--|--------------------|--------------|-------|
| Peak Pulse Power ( t <sub>P</sub> = 8/20µs )   | P <sub>PP</sub>    | 45           | W     |
| Peak Pulse Current ( t <sub>P</sub> = 8/20μs ) | I <sub>PP</sub>    | 6.0          | А     |
| Lead Soldering Temperature                     | T <sub>L</sub>     | 260 (10 sec) | °C    |
| Junction and Storage Temperature Range         | $T_{J_{I}}T_{STG}$ | -55~+150     | °C    |
| ESD Protection-Contact Discharge               | V <sub>ESD</sub>   | ±15          | kV    |
| ESD Protection-Air Discharge                   | V <sub>ESD</sub>   | ±15          | kV    |

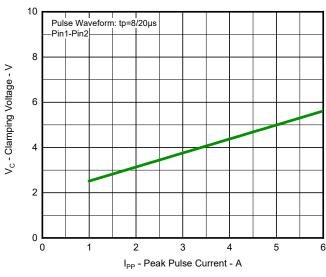
## **Typical Characteristics**



100 80 % Of Rated Power 60 40 20 0 25 0 50 75 100 125 150  $T_L$  – Lead Temperature -  $^{\circ}$ C

Fig 1.Pulse Waveform(8/20µs)

Fig 2.Power Derating Curve



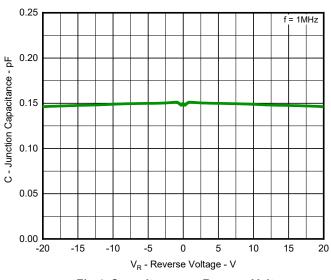
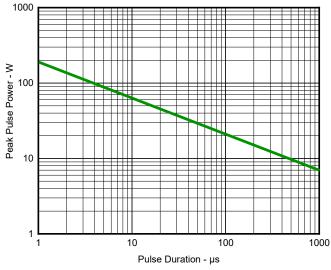


Fig 3. Clamping Voltage vs. Peak Pulse Current

Fig 4. Capacitance vs. Reveres Voltage 20



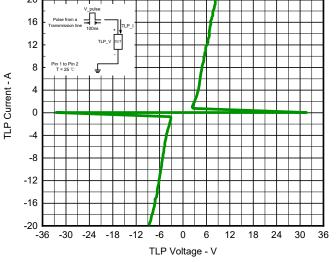
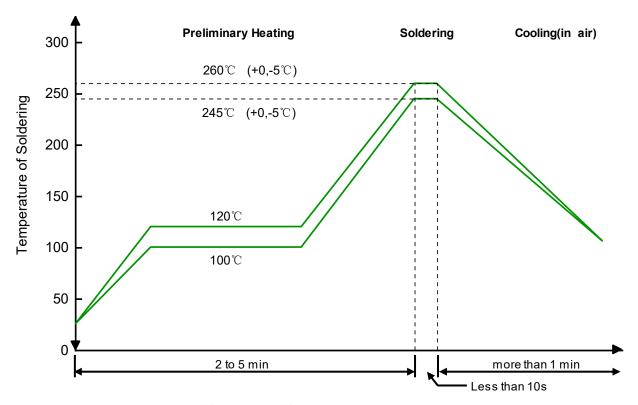


Fig 5. Non Repetitive Peak Pulse Power vs. Pulse Time

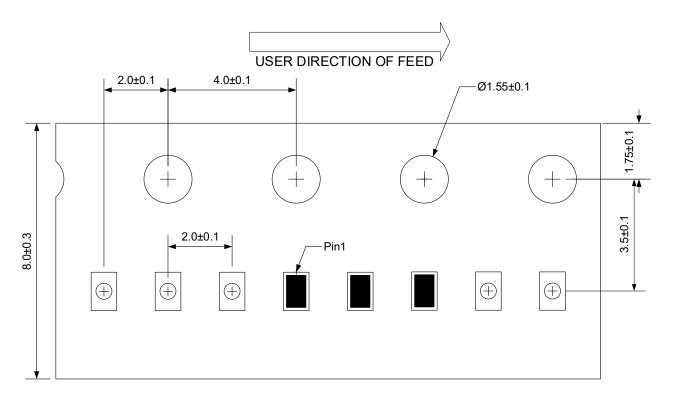
Fig 6. TLP Measurement

### **Solder Reflow Recommendation**



Remark: Pb free for 260°C; Pb for 245°C.

### Load with information



Unit:mm

### **Ordering information**

| Device          | Package    | Reel | Shipping            |
|-----------------|------------|------|---------------------|
| PESDREC2XD20VBX | DFN0603-2L | 7"   | 10000 / Tape & Reel |

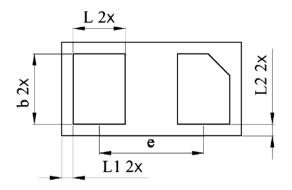
### **PCB** Design

For TVS diodes a low-ohmic and low-inductive path to chassis earth is absolutely mandatory in order to achieve good ESD protection. Novices in the area of ESD protection should take following suggestions to heart:

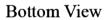
- > Do not use stubs, but place the cathode of the TVS diode directly on the signal trace.
- > Do not make false economies and save copper for the ground connection.
- Place via holes to ground as close as possible to the anode of the TVS diode.
- > Use as many via holes as possible for the ground connection.
- > Keep the length of via holes in mind! The longer the more inductance they will have.

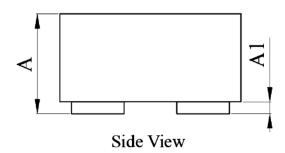
D

# Product dimension (DFN0603-2L)

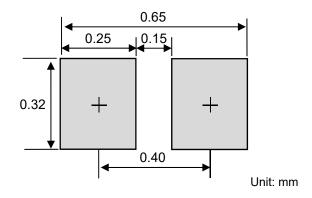


Top View





| Dim | Millim    | neters | Inches    |       |  |
|-----|-----------|--------|-----------|-------|--|
|     | Min       | Max    | Min       | Max   |  |
| Α   | 0.28      | 0.34   | 0.011     | 0.013 |  |
| A1  | 0.00      | 0.05   | 0.000     | 0.002 |  |
| b   | 0.215     | 0.265  | 0.008     | 0.010 |  |
| D   | 0.59      | 0.64   | 0.023     | 0.025 |  |
| E   | 0.29      | 0.34   | 0.011     | 0.013 |  |
| е   | 0.36 BSC  |        | 0.014 BSC |       |  |
| L   | 0.155     | 0.205  | 0.006     | 0.008 |  |
| L1  | 0.040 BSC |        | 0.002 BSC |       |  |
| L2  | 0.040 BSC |        | 0.002 BSC |       |  |



Suggested PCB Layout

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